

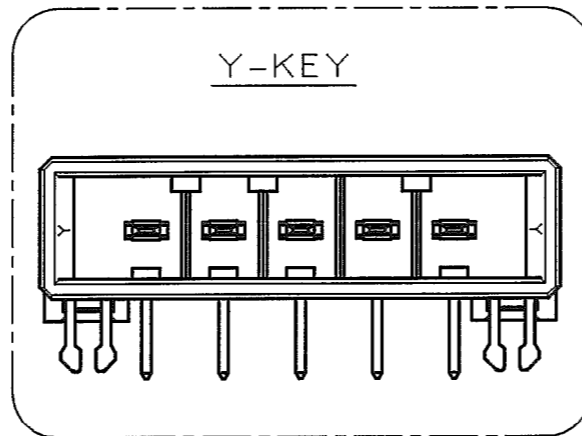
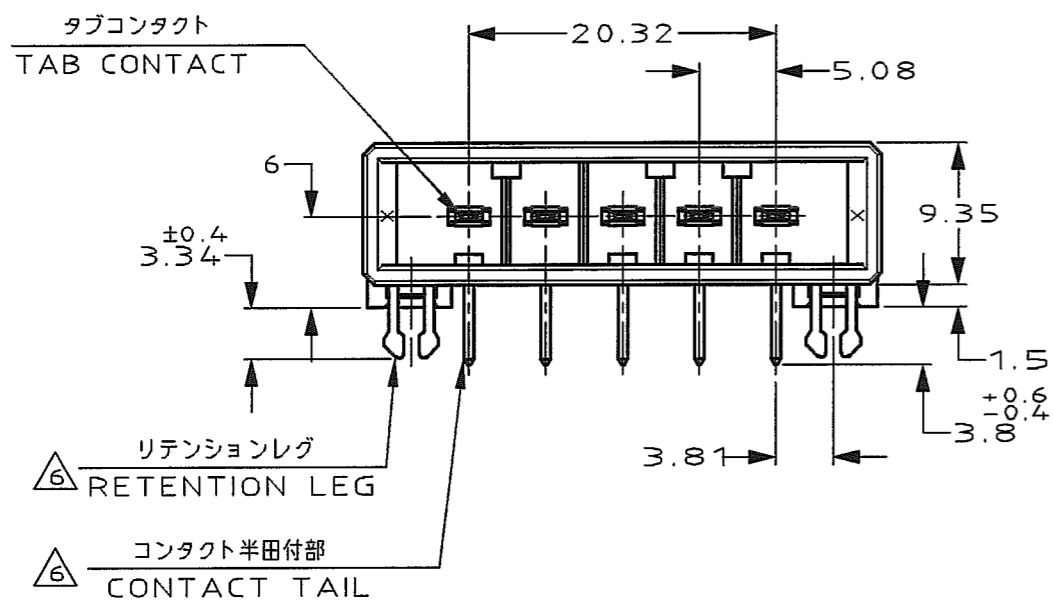
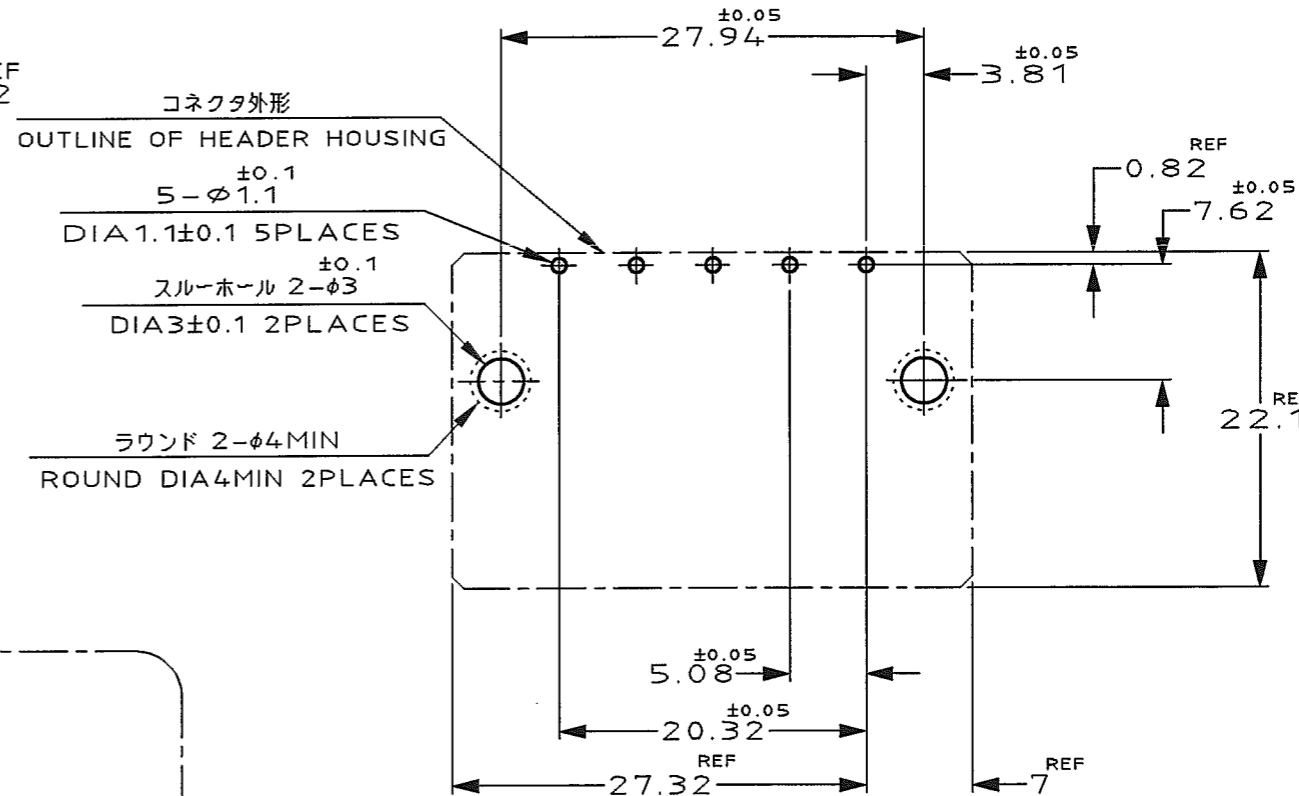
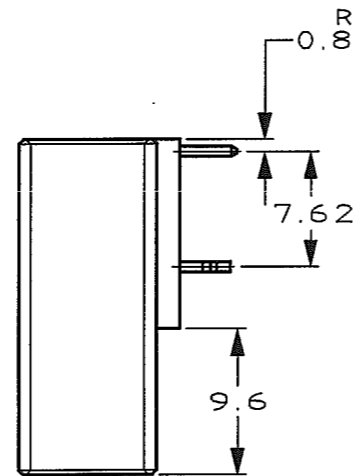
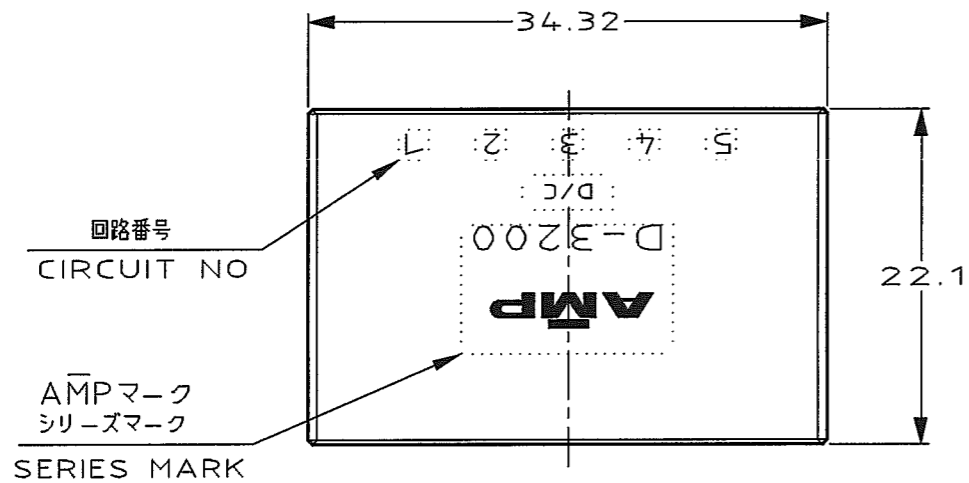
NUMBER 316130

3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法  
PC 基板厚: 1.6±0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6±0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂  
コンタクト: 銅合金  
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地  
接触部: 0.38 μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地  
接触部: 0.76 μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地  
接触部: 2.0 μm MINスズめっき
5. めっき: リテンションレグとコンタクト半田付部  
: ニッケル下地の上に半田めっき
6. めっき: リテンションレグとコンタクト半田付部  
: ニッケル下地の上にスズめっき

△6	△4	2-316130-5	Y	OBSOLETE
△6	△3	2-316130-3	Y	
△6	△2	2-316130-2	Y	
△6	△4	1-316130-5	X	
△6	△3	1-316130-3	X	
△6	△2	1-316130-2	X	
(FINISH)		製品番号 (PART NO.)	KEY	

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WIRE RANGE			INSULATION DIA		NAME	
mm(AWG - )			mmφ		5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL			FINISH		一般公差 (GENERAL TOLERANCE)	
SEE NOTE 注記参照			SEE NOTE 注記参照		100F : ±0.2 1000F 300F : ±0.3 3000F 1000F : ±0.4 再 尺 : ±3'	
DR. 26/JUL/95			DE. 26/JUL/95		SIZE LOC NUMBER	
K.IKEDA			K.IKEDA		A3 J C= 316130	
CHK. 31 JUL 95			APP. 31 JUL 95		SCALE REV. SHEET	
Y.ISHIKAWA			S. MANABE		2-1 B1 1 OF 1	